



Micro Systems Technologies
engineering for life

Interconnect Technology

- HDI/microvia PCBs in flex, rigid-flex and rigid technology
- Multilayer ceramic substrates based on LTCC and thick film technologies
- Packaging substrates
- LCP (Liquid Crystal Polymer) substrates

Interconnect Technology

The MST Group has extensive experience in designing and manufacturing electronic modules for medical devices and other high-reliability applications.

Interconnect technology is a crucial prerequisite for the production of miniaturized, highly reliable modules.

MST can offer a wide range of substrates – based on both organic and ceramic materials.

DYCONEX AG, an MST company located in Bassersdorf, Switzerland, is an expert and technology leader in HDI/microvia substrates based on flex, rigid-flex and rigid technology.

Micro Systems Engineering GmbH, an MST company located in Berg, Germany, is the leading European manufacturer of complex ceramic substrates in LTCC (Low Temperature Co-fired Ceramic) and thick film technologies.

CAPABILITIES AND SERVICES

DESIGN SERVICES

MST converts your design inputs and requirements into reliable and robust solutions. Assistance is offered for various technologies like HDI printed circuit boards, LTCC, thick film, HTCC (High Temperature Co-fired Ceramic) and thin film.

PRINTED CIRCUIT BOARDS AND CHIP PACKAGING SUBSTRATES

- High-reliability HDI/microvia substrates in flex, rigid-flex and rigid technology
- High-frequency/high-temperature applications
- Microfluidic substrates
- LCP (Liquid Crystal Polymer) substrates
- Comprehensive range of base materials, constraining materials and surface finishes
- Enhanced features such as embedded passives, wrap-around, cavities, etc.
- Substrates for BGAs, CSPs, SiPs, MCMs and folded packages

LTCC SUBSTRATES

- Excellent RF and microwave performance
- Hermetic and highly integrated packages
- Embedded passive components (capacitors, inductors, resistors)
- 3D solutions including stepped cavities and windows
- Brazing operations (metal plates, frames, pins)
- Mechanical processing (laser cutting, machining)

TEST SERVICES

A wide range of in-process and final inspection procedures, stress tests and other means of analysis is available to demonstrate the performance of the components.

QUALITY

The quality system of the MST Group derives from the stringent requirements of life-sustaining implants and assures 100% traceability of processes and materials.

MICRO SYSTEMS TECHNOLOGIES

Micro Systems Technologies Group (MST) consists of four technology companies that provide innovative products and services for medical devices and other high-reliability/high-performance industries. The offering includes HDI/microvia PCBs, ceramic substrates, assembly and semiconductor packaging processes, electronic module design and manufacturing, as well as batteries and battery packs for medical implants.

The MST Companies:

DYCONEX AG

LITRONIK Batterietechnologie GmbH

Micro Systems Engineering GmbH

Micro Systems Engineering, Inc.



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